



PRODUCTS

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IT-140GBS No Flow Prepreg

Medium Tg, Halogen Free Multifunctional Filled Epoxy Resin

IT-140G no/low flow prepreg is a halogen free medium Tg (>140 °C by DSC) multifunctional filled epoxy. It's designed for rigid flex board and heat sink bonding application.

Key Features =====

Advanced Resin Technology

Medium Tg (140 °C by DSC) halogen free, excellent thermal reliability and CAF resistance. Br and Cl are less than 900ppm respectively. Total halogen contents are less than 1500ppm.

Lead-Free Assembly Compatible

RoHS compliant and suitable for high thermal reliability needs, and Lead free assemblies with a maximum reflow temperature of 260 °C.

Prepreg Availability

The glass styles of 1080, 1078, 1067 Prepreg are available that contain 20-120mil circular flow for different customer's designs and applications.

Applications

Rigid Flex Boards

Heat Sink Bonding

Cavity PCB Design

Industrial Approval

UL 94 V-0

RoHS Compliant



IT-140GBS No Flow Prepreg

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Properties

IT-140G NF Properties (Laminated Prepreg)	Typical Values	Units	Test Methods
			IPC-TM-650
Glass Transition Temperature (Tg)- DSC	150	°C	2.4.25 2.4.24
Decomposition Temperature (Td)	348	°C	2.4.24.6 (5% wt loss)
Permittivity (Dk) @ 1 MHz	3.8	---	2.5.5.9
Loss Tangent (Df) @ 1 MHz	0.013	---	2.5.5.9
Volume Resistivity, minimum C-96/ 35/ 90 After Moisture Resistance At Elevated Temperature: E- 24/ 125	10 ¹⁰ 10 ¹⁰ 10 ¹⁰	MΩ-cm	2.5.17.1
Surface Resistivity, minimum C-96/ 35/ 90 After Moisture Resistance At Elevated Temperature: E- 24/ 125	10 ¹⁰ 10 ¹⁰ 10 ¹⁰	MΩ	2.5.17.1
Electric Strength, minimum	45	kV/ mm	2.5.6.2
Arc Resistance, minimum	90	Sec	2.5.1
Dielectric Breakdown, minimum	60	kV	2.5.6
Peel Strength, As received- 1oz copper	8	lb/ in ²	2.4.8
Moisture Absorption, maximum	0.12	%	2.6.2.1
Flammability	V-0	Rating	UL 94

Data are based on 8 plies 1067 Laminated prepreg

Prepreg Specification

Glass Style	Resin Content (%)	Circular Flow (mil)	Pressed Thickness (mil)
1080	65+/-2	20-120	3.3+/-0.3
	63+/-2	20-120	3.1+/-0.3
1078	62+/-2	20-120	2.9+/-0.3
1067	71.5+/-2	20-120	2.6+/-0.3
	65+/-2	20-120	2.0+/-0.3

The above data and fabrication guide provide designers and PCB shop for their reference. We believe that these information are accurate, however, the data may vary depend on the test methods and specification used. The actual sales of the product should be according to specification in the agreement between ITEQ and its customer. ITEQ reserves the right to revise its data at any time without notice and maintain the best information available to users.